## **OINA Blank PCB Specification**

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PCB Part Number 51-G-1384-480-02

Overall Size 55 x 88 mm Board extents 55.0 x 88 mm

Overall Thickness  $0.6 \text{mm mm} \pm 10\%$ 

Layers 2 Substrate Material FR4

Board surface Finish Immersion Silver □ Nickel/Gold ☑

Bare Board Test Yes

Special Instructions/finishes IPC-A-600 Flammability FV-1 or IEC 60707

Release Status Required None □ C of C □ UL94V-0 ☑ ISO9000 ☑ RoHS ☑

Finished board must be compatible with Lead-Free assembly.

Plated Holes			Unplated Holes			
Sizes	Total	Min Hole Size	Sizes	Total	Min Hole Size	
3	102	0.3 mm	2	3	0.9mm	

Track Details		Net/Pin Details			
Min track width Min track clearance		Number of Nets	Number of pins/pads		
200 μm	200 μm				

Drill data file		
	Specification	File
Plated		PCB_Card-PTH.drl (gerber, PDF and post script also provided)
Plated Non Round		
Non Plated		PCB_Card-NPTH.drl (gerber, PDF and post script also provided)
Non-Plated Non Round		

Layer Build	Specification	File name		
Solder paste mask (top)		PCB_Card-F.Paste.gbr		
Silk (top)	White	PCB_Card-F.SilkS.gbr		
Resist (top)	Blue	PCB_Card-F.Mask.gbr		
Copper Layer 1	35μm (1oz) after plating	PCB_Card-F.Cu.gbr		
Dielectric	FR4			
Copper Layer 2	35μm (1oz) after plating	PCB_Card-B.Cu.gbr		
Resist (bottom)	Blue	PCB_Card-B.Mask.gbr		
Silk (bottom)	White	PCB_Card-B.SilkS.gbr		
Solder paste mask (bottom)	None			

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